Section 1 of Page 1 of Specification

METHOD OF MANUFACTURING SEMICONDUCTOR PACKAGES

AND A CLAMPING DEVICE FOR MANUFACTURING A SEMICONDUCTOR

PACKAGE

FIELD OF THE INVENTION

The present invention relates to a method of manufacturing semiconductor packages and to a clamping device for manufacturing a semiconductor package, and more particularly, to a method of manufacturing semiconductor packages using a jig fixture comprising a submold and to a clamping device for manufacturing a semiconductor package in a mold.

1